PTO/SB/08 (10-92)
Sheet 1 of _

FORM PTO-1449	Docket Number (Optional): JETS-02	Application Number:
INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	Applicant: Uri Cohen	
	Filing Date: 10/17/2003	Group Art Unit:

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
NW	3 6 5 2 4 4 2	03/28/72	Powers et al.	204	273	
	3 7 4 3 5 9 0	07/03/73	Roll	204	212	
	3 9 6 3 5 8 8	06/15/76	Glenn	204	16	
	4 1 0 2 7 5 6	07/25/78	Castellani et al.	204	43	
	4 2 6 7 0 2 4	05/12/81	Weiskopf et al.	204	15	
	4 2 7 9 7 0 7	07/21/81	Anderson et al.	204	43	
	4 3 0 4 6 4 1	12/08/81	Grandia et al.	204	23	
	4 3 5 9 3 7 5	11/16/82	Smith	204	212	
	4 3 6 4 8 0 1	12/21/82	Salama	204	15	
NW	4 5 0 0 3 9 4	02/19/85	Rizzo	204	15	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES	Translation NO

NON-PATENT LITERATURE DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

NW	1	M. Matlosz, "Competitive Adsorption Effects in the Electrodeposition of Iron-Nickel Alloys", J. Electrochem. Soc. Vol. 140(8), August 1993, pp. 2272-2279.
NW	2.	P. C. Andricacos et al., "Electrodeposition of Nickel-Iron Alloys", J. Electrochem. Soc. Vol 136(5), May 1989, pp. 1336-1340.
NW	3	A. R. DESPIC and K. I. POPOV, "Transport-Controlled Deposition and Dissolution of Metals", in Modern Aspect of Electrochemistry, Vol. 7, Edited by B. E. CONWAY and J. O'M. BOCKRIS, pp. 256-268, Plenum Press, N.Y. 1972.
NW	4	E. H. LYONS, "Fundamental Principles", in Modern Electroplating, 3rd Edition, edited by F. A. LOWENHEIM, pp. 31-36, John Wiley & Sons, 1974.
NW	5	J. JORNE, Challenges in Copper Interconnect Technology: Macro-Uniformity and Micro-Filling Power in Copper Electroplating of Wafers", in Semiconductor Fabtech - 11th Edition, pp. 267-271, February 2000.
NW	6	U. COHEN and G. TZANAVARAS, "Seed Layers and Cu Jets Plating for Interconnects Below 0.10 Micron", in the 17th VLSI Multilevel Interconncetion Conference (VMIC), pp. 21-26, Santa Clara, California, June 2000.

EXAMINER	DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.